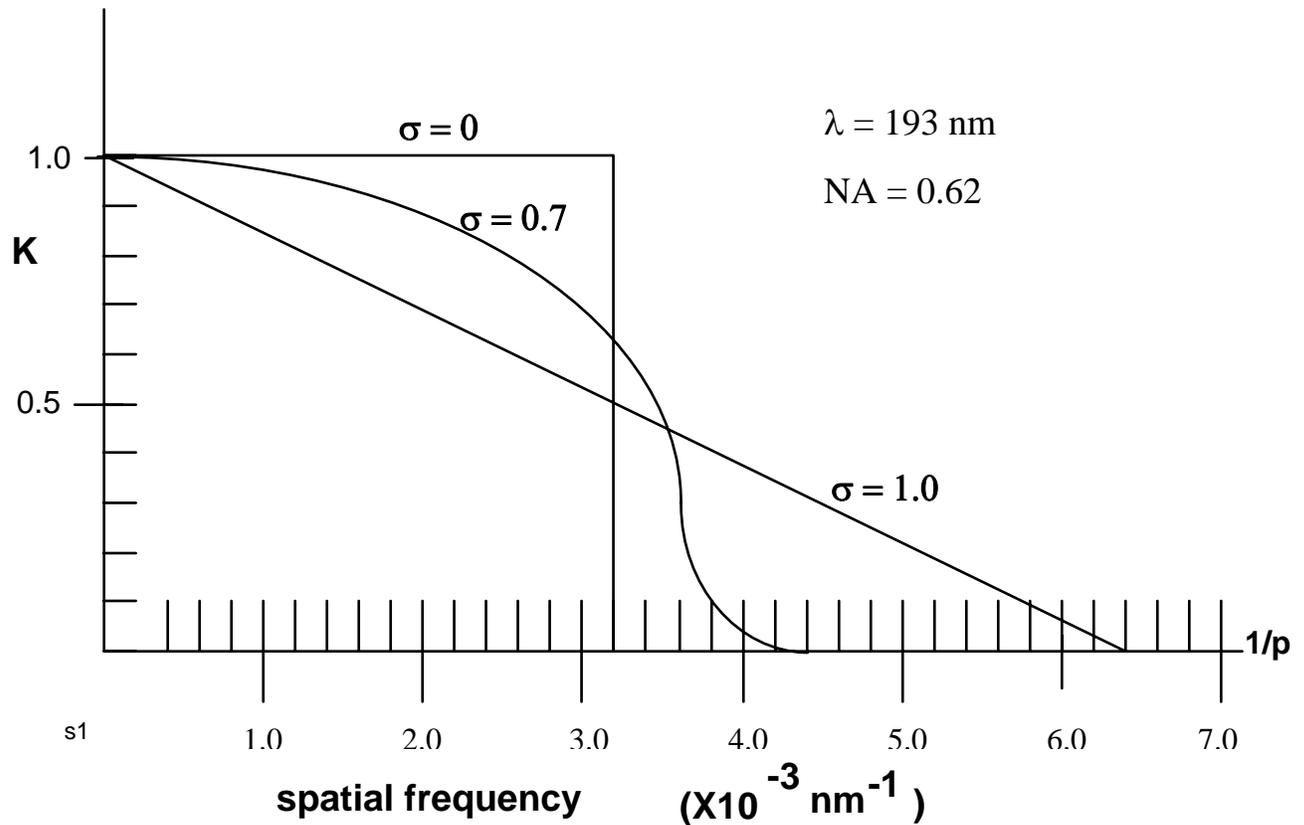


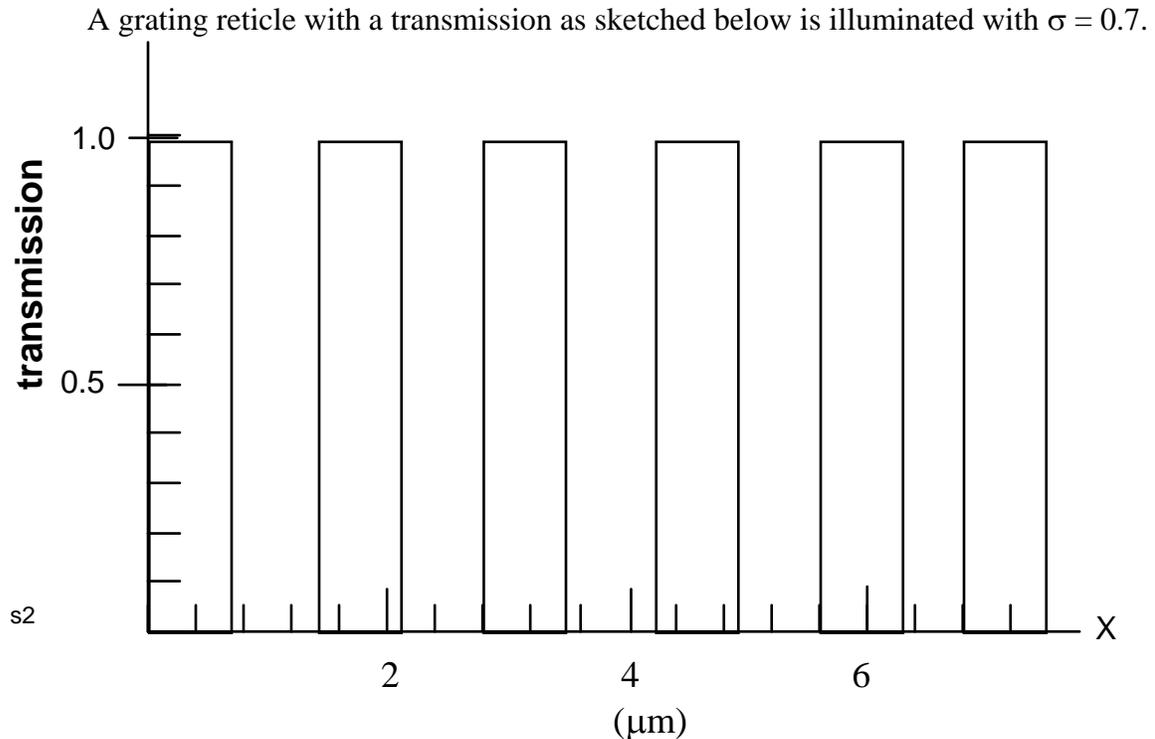
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Submicrometer and Nanometer Technology
Homework Set #12

12-1

An optical projection system with a numerical aperture of 0.62, a demagnification factor of 4X, a field diameter of 20 mm, and an operating wavelength of 193 nm (ArF excimer laser) is characterized by the following dependence of contrast, K , on spatial frequency, $1/p$, for 3 values of the aperture filling, σ .



(over)



- What is the contrast, K , in the image of this reticle?
- What fraction of the zero-order diffraction cone falls within the entrance aperture?
- What fraction of the 1st order diffraction cone falls within the entrance aperture?
- What fraction of the 2nd order diffraction cone falls within the entrance aperture?
- What is the ratio $I_{\text{max}}/I_{\text{min}}$ in the image?
- Plot the irradiance (intensity) distribution of the image.
- Calculate the approximate depth of focus.

Assume that the substrate is coated with a special resist, type MIT-1, whose development rate, R , is linearly proportional to the energy absorbed per unit volume, E .

$$R_{(\text{nm}/\text{sec})} = a E_{(\text{erg}/\text{cm}^3)}$$

The energy absorbed per unit volume, E , is, of course, proportional to the product of the intensity (ergs/cm²) and the exposure time, t .

$$E \propto It$$

Assume that you expose a 1- μ m-thick film for a sufficiently long time that the development rate at the point of maximum intensity is $R = 100$ nm/sec. Also assume that the energy absorbed is uniform with depth in the resist (an unrealistic assumption). Thus, development rate will vary as a function of x only.

$$R = R(x)$$

- h) What development time should be used to achieve equal widths for the spaces and the lines.
- i) Sketch the resist profile.